

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.93435	100.0	1.1
			Subtotal	0.93435	100	1.1
Wire	Impurity	Non hazardous		0.00001	0.01	0.00001
	Pure metal	Copper (Cu)	7440-50-8	0.06688	99.99	0.07874
			Subtotal	0.06689	100	0.07875
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02593	0.05	0.03053
	Copper alloy	Zinc (Zn)	7440-66-6	0.05186	0.1	0.06105
	Copper alloy	Iron (Fe)	7439-89-6	1.1927	2.3	1.40415
	Copper alloy	Copper (Cu)	7440-50-8	50.58601	97.55	59.55427
			Subtotal	51.8565	100	61.05
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.48416	100.0	0.57
			Subtotal	0.48416	100	0.57
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.68713	1.5	0.80895
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.35183	9.5	5.12335
	Filler	Silica fused	60676-86-0	40.31165	88.0	47.4584
	Carbon Black	Carbon black	1333-86-4	0.45809	1.0	0.5393
			Subtotal	45.8087	100	53.93
Die Attach		Aromatic Polyester Resin	60088-52-0	0.02124	2.5	0.025
		Paraffin wax	8002-74-2	0.05946	7.0	0.07
		Epoxy resin system		0.16988	20.0	0.2
		Silver (Ag)	7440-22-4	0.59883	70.5	0.705
			Subtotal	0.84941	100	1
			Total	100.00001	100	117.72875

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